

# 2.5 V/3.3 V Any Level Positive Input to -2.5 V/-3.3 V LVNECL Output Translator

## NB100LVEP91

### Description

The NB100LVEP91 is a triple any level positive input to NECL output translator. The device accepts LVPECL, LVTTTL, LVCMOS, HSTL, CML or LVDS signals, and translates them to differential LVNECL output signals ( $-2.5\text{ V}/-3.3\text{ V}$ ).

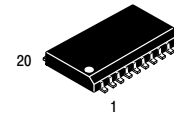
To accomplish the level translation the LVEP91 requires three power rails. The  $V_{CC}$  pins should be connected to the positive power supply, and the  $V_{EE}$  pin should be connected to the negative power supply. The GND pins are connected to the system ground plane. Both  $V_{EE}$  and  $V_{CC}$  should be bypassed to ground via  $0.01\text{ }\mu\text{F}$  capacitors.

Under open input conditions, the  $\bar{D}$  input will be biased at  $V_{CC}/2$  and the D input will be pulled to GND. These conditions will force the Q outputs to a low state, and Q outputs to a high state, which will ensure stability.

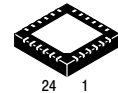
The  $V_{BB}$  pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to  $V_{BB}$  as a switching reference voltage.  $V_{BB}$  may also rebias AC coupled inputs. When used, decouple  $V_{BB}$  and  $V_{CC}$  via a  $0.01\text{ }\mu\text{F}$  capacitor and limit current sourcing or sinking to  $0.5\text{ mA}$ . When not used,  $V_{BB}$  should be left open.

### Features

- Maximum Input Clock Frequency > 2.0 GHz Typical
- Maximum Input Data Rate > 2.0 Gb/s Typical
- 500 ps Typical Propagation Delay
- Operating Range:
  - ◆  $V_{CC} = 2.375\text{ V}$  to  $3.8\text{ V}$ ;  $V_{EE} = -2.375\text{ V}$  to  $-3.8\text{ V}$ ; GND =  $0\text{ V}$
- Q Output will Default LOW with Inputs Open or at GND
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

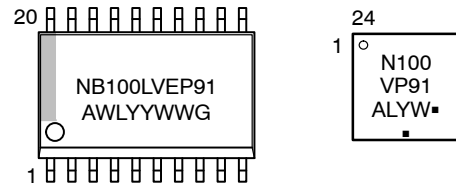


SOIC-20 WB  
DW SUFFIX  
CASE 751D-05



QFN-24  
MN SUFFIX  
CASE 485L-01

### MARKING DIAGRAMS\*



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

| Device           | Package              | Shipping†        |
|------------------|----------------------|------------------|
| NB100LVEP91DWG   | SOIC-20 WB (Pb-Free) | 38 Units/Tube    |
| NB100LVEP91DWR2G | SOIC-20 WB (Pb-Free) | 1000/Tape & Reel |
| NB100LVEP91MNG   | QFN-24 (Pb-Free)     | 92 Units/Tube    |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

# NB100LVEP91

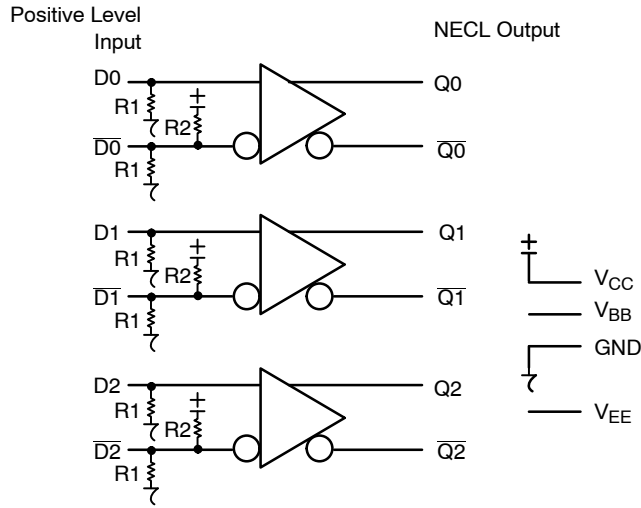


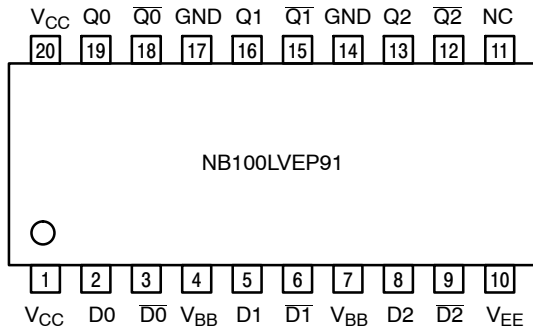
Figure 1. Logic Diagram

Table 1. PIN DESCRIPTION

| Pin        |                | Name            | I/O                                           | Default State | Description                                                                                                                                                     |
|------------|----------------|-----------------|-----------------------------------------------|---------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------|
| SOIC       | QFN            |                 |                                               |               |                                                                                                                                                                 |
| 1, 20      | 3, 4, 12       | V <sub>CC</sub> | –                                             | –             | Positive Supply Voltage. All V <sub>CC</sub> Pins must be Externally Connected to Power Supply to Guarantee Proper Operation.                                   |
| 10         | 15, 16         | V <sub>EE</sub> | –                                             | –             | Negative Supply Voltage. All V <sub>EE</sub> Pins must be Externally Connected to Power Supply to Guarantee Proper Operation.                                   |
| 14, 17     | 19, 20, 23, 24 | GND             | –                                             | –             | Ground.                                                                                                                                                         |
| 4, 7       | 7, 11          | V <sub>BB</sub> | –                                             | –             | ECL Reference Voltage Output                                                                                                                                    |
| 2, 5, 8    | 5, 8, 13       | D[0:2]          | LVPECL, LVDS, LVTTTL, LVCMOS, CML, HSTL Input | Low           | Non-inverted Differential Inputs [0:2]. Internal 75 kΩ to GND.                                                                                                  |
| 3, 6, 9    | 6, 9, 14       | D̄[0:2]         | LVPECL, LVDS, LVTTTL, LVCMOS, CML, HSTL Input | High          | Inverted Differential Inputs [0:2]. Internal 75 kΩ to GND and 75 kΩ to V <sub>CC</sub> . When Inputs are Left Open They Default to (V <sub>CC</sub> – GND) / 2. |
| 19, 16, 13 | 2, 22, 18      | Q[0:2]          | LVNECL Output                                 | –             | Non-inverted Differential Outputs [0:2]. Typically Terminated with 50 Ω to V <sub>TT</sub> = V <sub>CC</sub> – 2 V                                              |
| 18, 15, 12 | 1, 21, 17      | Q̄[0:2]         | LVNECL Output                                 | –             | Inverted Differential Outputs [0:2]. Typically Terminated with 50 Ω to V <sub>TT</sub> = V <sub>CC</sub> – 2 V                                                  |
| 11         | 10             | NC              | –                                             | –             | No Connect. The NC Pin is NOT Electrically Connected to the Die and may Safely be Connected to Any Voltage from V <sub>EE</sub> to V <sub>CC</sub> .            |
| N/A        | –              | EP              | –                                             | –             | Exposed Pad. (Note 1)                                                                                                                                           |

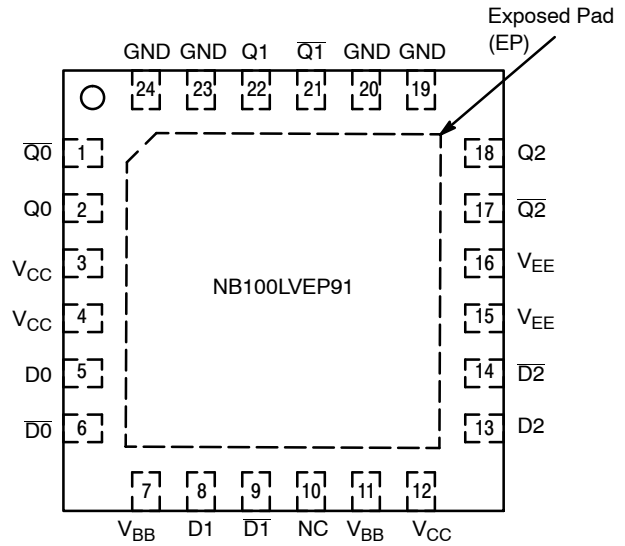
1. The thermally conductive exposed pad on the package bottom (see case drawing) must be attached to a heat sinking conduit and may only be electrically connected to V<sub>EE</sub> (not GND).

# NB100LVEP91



**Figure 2. SOIC-20 WB Lead Pinout (Top View)\***

\*All V<sub>CC</sub>, V<sub>EE</sub> and GND pins must be externally connected to a power supply.



**Figure 3. QFN-24 Lead Pinout (Top View)\***

\*All V<sub>CC</sub>, V<sub>EE</sub> and GND pins must be externally connected to a power supply. The thermally conductive exposed pad on the package bottom (see case drawing) must be attached to a sufficient heat-sinking conduit and may only be electronically connected to V<sub>EE</sub> (not GND).

**Table 2. ATTRIBUTES**

| Characteristics                                                             | Value                       |
|-----------------------------------------------------------------------------|-----------------------------|
| Internal Input Pulldown Resistor (R1)                                       | 75 kΩ                       |
| Internal Input Pullup Resistor (R2)                                         | 75 kΩ                       |
| ESD Protection<br>Human Body Model<br>Machine Model<br>Charged Device Model | > 2 kV<br>> 150 V<br>> 2 kV |
| Moisture Sensitivity (Note 1)                                               | Pb-Free Pkg                 |
| SOIC-20 WB<br>QFN-24                                                        | Level 3<br>Level 1          |
| Flammability Rating<br>Oxygen Index: 28 to 34                               | UL 94 V-0 @ 0.125 in        |
| Transistor Count                                                            | 446 Devices                 |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test                      |                             |

1. For additional information, see Application Note [AND8003/D](#).

# NB100LVEP91

**Table 3. MAXIMUM RATINGS**

| Symbol           | Parameter                                                                                                   | Condition 1         | Condition 2                       | Rating         | Unit |
|------------------|-------------------------------------------------------------------------------------------------------------|---------------------|-----------------------------------|----------------|------|
| V <sub>CC</sub>  | Positive Power Supply                                                                                       | GND = 0 V           |                                   | 3.8 to 0       | V    |
| V <sub>EE</sub>  | Negative Power Supply                                                                                       | GND = 0 V           |                                   | –3.8 to 0      | V    |
| V <sub>I</sub>   | Positive Input Voltage                                                                                      | GND = 0 V           | V <sub>I</sub> ≤ V <sub>CC</sub>  | 3.8 to 0       | V    |
| V <sub>OP</sub>  | Operating Voltage                                                                                           | GND = 0 V           | V <sub>CC</sub> – V <sub>EE</sub> | 7.6 to 0       | V    |
| I <sub>out</sub> | Output Current                                                                                              | Continuous<br>Surge |                                   | 50<br>100      | mA   |
| I <sub>BB</sub>  | PECL V <sub>BB</sub> Sink/Source                                                                            |                     |                                   | ±0.5           | mA   |
| T <sub>A</sub>   | Operating Temperature Range                                                                                 |                     |                                   | –40 to +85     | °C   |
| T <sub>stg</sub> | Storage Temperature Range                                                                                   |                     |                                   | –65 to +150    | °C   |
| θ <sub>JA</sub>  | Thermal Resistance (Junction-to-Ambient)<br>JESD 51–3 (1S-Single Layer Test Board)                          | 0 lfpm<br>500 lfpm  | SOIC–20 WB                        | 90<br>60       | °C/W |
| θ <sub>JA</sub>  | Thermal Resistance (Junction-to-Ambient)<br>JESD 51–6 (2S2P Multilayer Test Board) with Filled Thermal Vias | 0 lfpm<br>500 lfpm  | QFN–24                            | 37<br>32       | °C/W |
| θ <sub>JC</sub>  | Thermal Resistance (Junction-to-Case)                                                                       | Standard<br>Board   | SOIC–20 WB<br>QFN–24              | 30 to 35<br>11 | °C/W |
| T <sub>sol</sub> | Wave Solder (Pb-Free)                                                                                       |                     |                                   | 225            | °C   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**Table 4. DC CHARACTERISTICS POSITIVE INPUTS** (V<sub>CC</sub> = 2.5 V, V<sub>EE</sub> = –2.375 to –3.8 V, GND = 0 V (Note 1))

| Symbol             | Characteristic                                                                | –40°C       |     |                 | 25°C        |     |                 | 85°C        |     |                 | Unit |
|--------------------|-------------------------------------------------------------------------------|-------------|-----|-----------------|-------------|-----|-----------------|-------------|-----|-----------------|------|
|                    |                                                                               | Min         | Typ | Max             | Min         | Typ | Max             | Min         | Typ | Max             |      |
| I <sub>CC</sub>    | Positive Power Supply Current                                                 | 10          | 14  | 20              | 10          | 14  | 20              | 10          | 14  | 20              | mA   |
| V <sub>IH</sub>    | Input HIGH Voltage (Single-Ended)                                             | 1335        |     | V <sub>CC</sub> | 1335        |     | V <sub>CC</sub> | 1335        |     | V <sub>CC</sub> | mV   |
| V <sub>IL</sub>    | Input LOW Voltage (Single-Ended)                                              | GND         |     | 875             | GND         |     | 875             | GND         |     | 875             | mV   |
| V <sub>IHCMR</sub> | Input HIGH Voltage Common Mode Range<br>(Differential Configuration) (Note 2) | 0           |     | 2.5             | 0           |     | 2.5             | 0           |     | 2.5             | V    |
| I <sub>IH</sub>    | Input HIGH Current (@ V <sub>IH</sub> )                                       |             |     | 150             |             |     | 150             |             |     | 150             | μA   |
| I <sub>IL</sub>    | Input LOW Current (@ V <sub>IL</sub> )<br>D<br>D̄                             | 0.5<br>–150 |     |                 | 0.5<br>–150 |     |                 | 0.5<br>–150 |     |                 | μA   |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- Input parameters vary 1:1 with V<sub>CC</sub>. V<sub>CC</sub> can vary +1.3 V / –0.125 V.
- V<sub>IHCMR</sub> min varies 1:1 with GND. V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>.

# NB100LVEP91

**Table 5. DC CHARACTERISTICS POSITIVE INPUT** ( $V_{CC} = 3.3 \text{ V}$ ;  $V_{EE} = -2.375 \text{ V}$  to  $-3.8 \text{ V}$ ;  $GND = 0 \text{ V}$  (Note 1))

| Symbol      | Characteristic                                                             | -40°C |      |          | 25°C |      |          | 85°C |      |          | Unit          |
|-------------|----------------------------------------------------------------------------|-------|------|----------|------|------|----------|------|------|----------|---------------|
|             |                                                                            | Min   | Typ  | Max      | Min  | Typ  | Max      | Min  | Typ  | Max      |               |
| $I_{CC}$    | Positive Power Supply Current                                              | 10    | 16   | 24       | 10   | 16   | 24       | 10   | 16   | 24       | mA            |
| $V_{IH}$    | Input HIGH Voltage (Single-Ended)                                          | 2135  |      | $V_{CC}$ | 2135 |      | $V_{CC}$ | 2135 |      | $V_{CC}$ | mV            |
| $V_{IL}$    | Input LOW Voltage (Single-Ended)                                           | GND   |      | 1675     | GND  |      | 1675     | GND  |      | 1675     | mV            |
| $V_{BB}$    | PECL Output Voltage Reference                                              | 1775  | 1875 | 1975     | 1775 | 1875 | 1975     | 1775 | 1875 | 1975     | mV            |
| $V_{IHCMR}$ | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 2) | 0     |      | 3.3      | 0    |      | 3.3      | 0    |      | 3.3      | V             |
| $I_{IH}$    | Input HIGH Current (@ $V_{IH}$ )                                           |       |      | 150      |      |      | 150      |      |      | 150      | $\mu\text{A}$ |
| $I_{IL}$    | Input LOW Current (@ $V_{IL}$ )                                            |       |      |          |      |      |          |      |      |          | $\mu\text{A}$ |
|             | $\overline{D}$                                                             | 0.5   |      |          | 0.5  |      |          | 0.5  |      |          |               |
|             | $\overline{\overline{D}}$                                                  | -150  |      |          | -150 |      |          | -150 |      |          |               |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary  $+0.5 / -0.925 \text{ V}$ .
2.  $V_{IHCMR}$  min varies 1:1 with GND.  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ .

**Table 6. DC CHARACTERISTICS NECL OUTPUT** ( $V_{CC} = 2.375 \text{ V}$  to  $3.8 \text{ V}$ ;  $V_{EE} = -2.375 \text{ V}$  to  $-3.8 \text{ V}$ ;  $GND = 0 \text{ V}$  (Note 1))

| Symbol   | Characteristic                | -40°C |       |       | 25°C  |       |       | 85°C  |       |       | Unit |
|----------|-------------------------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|------|
|          |                               | Min   | Typ   | Max   | Min   | Typ   | Max   | Min   | Typ   | Max   |      |
| $I_{EE}$ | Negative Power Supply Current | 40    | 50    | 60    | 38    | 50    | 68    | 38    | 50    | 68    | mA   |
| $V_{OH}$ | Output HIGH Voltage (Note 2)  | -1145 | -1020 | -895  | -1145 | -1020 | -895  | -1145 | -1020 | -895  | mV   |
| $V_{OL}$ | Output LOW Voltage (Note 2)   | -1945 | -1770 | -1600 | -1945 | -1770 | -1600 | -1945 | -1770 | -1600 | mV   |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Output parameters vary 1:1 with GND.
2. All loading with  $50 \Omega$  resistor to GND - 2.0 V.

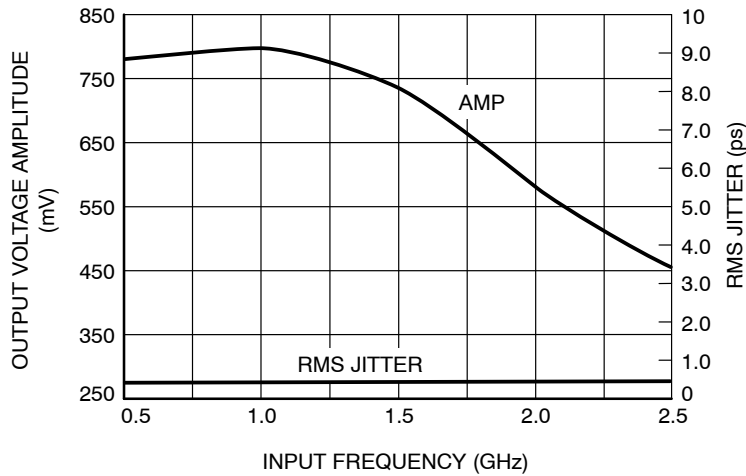
# NB100LVEP91

**Table 7. AC CHARACTERISTICS** ( $V_{CC} = 2.375 \text{ V}$  to  $3.8 \text{ V}$ ;  $V_{EE} = -2.375 \text{ V}$  to  $-3.8 \text{ V}$ ;  $GND = 0 \text{ V}$ )

| Symbol                  | Characteristic                                                                                                                               | -40°C             |                   |                 | 25°C              |                   |                  | 85°C              |                   |                  | Unit |
|-------------------------|----------------------------------------------------------------------------------------------------------------------------------------------|-------------------|-------------------|-----------------|-------------------|-------------------|------------------|-------------------|-------------------|------------------|------|
|                         |                                                                                                                                              | Min               | Typ               | Max             | Min               | Typ               | Max              | Min               | Typ               | Max              |      |
| $V_{OUTPP}$             | Output Voltage Amplitude (Figure 4) (Note 1)<br>$f_{in} \pm 1.0 \text{ GHz}$<br>$f_{in} \pm 1.5 \text{ GHz}$<br>$f_{in} \pm 2.0 \text{ GHz}$ | 575<br>525<br>300 | 800<br>750<br>600 |                 | 600<br>525<br>250 | 800<br>750<br>550 |                  | 550<br>400<br>150 | 800<br>750<br>500 |                  | mV   |
| $t_{PLH}$<br>$t_{PHLO}$ | Propagation Delay<br>Differential<br>D to Q<br>Single-Ended                                                                                  | 375<br>300        | 500<br>450        | 600<br>650      | 375<br>300        | 500<br>450        | 600<br>675       | 400<br>300        | 550<br>500        | 650<br>750       | ps   |
| $t_{SKEW}$              | Pulse Skew (Note 2)<br>Output-to-Output (Note 3)<br>Part-to-Part (Diff) (Note 3)                                                             |                   | 15<br>25<br>50    | 75<br>95<br>125 |                   | 15<br>30<br>50    | 75<br>105<br>125 |                   | 15<br>30<br>70    | 80<br>105<br>150 | ps   |
| $t_{JITTER}$            | RMS Random Clock Jitter (Note 4)<br>$f_{in} = 2.0 \text{ GHz}$<br>Peak-to-Peak Data Dependant Jitter (Note 5)<br>$f_{in} = 2.0 \text{ Gb/s}$ |                   | 0.5<br>20         | 2.0             |                   | 0.5<br>20         | 2.0              |                   | 0.5<br>20         | 2.0              | ps   |
| $V_{INPP}$              | Input Voltage Swing (Differential Configuration)<br>(Note 6)                                                                                 | 200               | 800               | 1200            | 200               | 800               | 1200             | 200               | 800               | 1200             | mV   |
| $t_r, t_f$              | Output Rise/Fall Times @ 50 MHz<br>(20% – 80%) Q, Q                                                                                          | 75                | 150               | 250             | 75                | 150               | 250              | 75                | 150               | 275              | ps   |

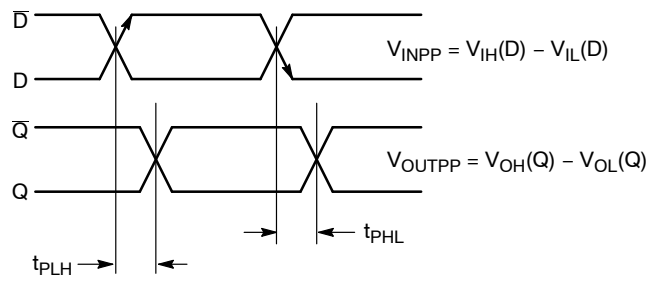
NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

1. Measured using a 750 mV source, 50% duty cycle clock source. All loading with  $50 \Omega$  to GND – 2.0 V. Input edge rates 150 ps (20% – 80%).
2. Pulse Skew =  $|t_{PLH} - t_{PHL}|$
3. Skews are valid across specified voltage range, part-to-part skew is for a given temperature.
4. RMS Jitter with 50% Duty Cycle Input Clock Signal.
5. Peak-to-Peak Jitter with input NRZ PRBS  $2^{31}-1$  at 2.0 Gb/s.
6. Input voltage swing is a single-ended measurement operating in differential mode. The device has a DC gain of  $\approx 50$ .



**Figure 4. Output Voltage Amplitude ( $V_{OUTPP}$ ) / RMS Jitter vs. Input Frequency ( $f_{in}$ ) at Ambient Temperature (Typical)**

# NB100LVEP91

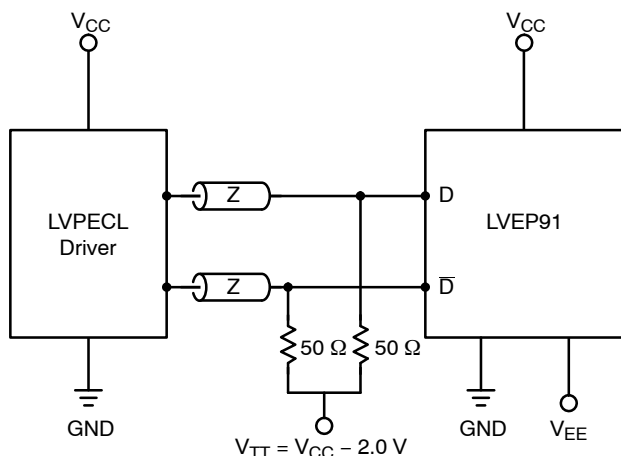


**Figure 5. AC Reference Measurement**

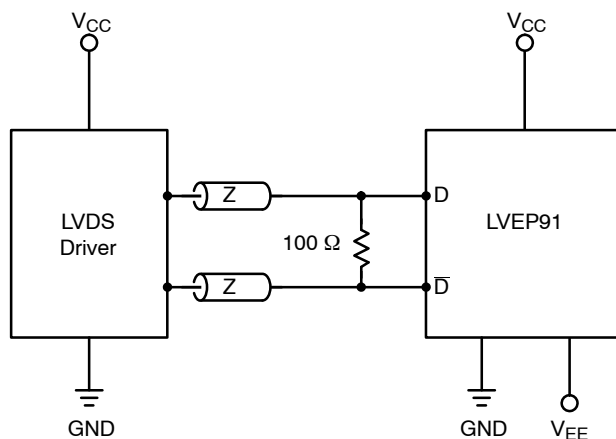
## Application Information

All NB100LVEP91 inputs can accept LVPECL, LVTTTL, LVC MOS, HSTL, CML, or LVDS signal levels. The limitations for differential input signal (LVDS, HSTL, LVPECL, or CML) are the minimum input swing of 150 mV

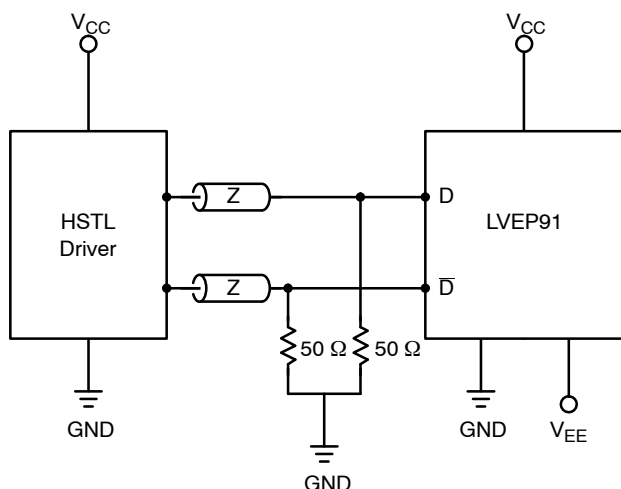
and the maximum input swing of 3.0 V. Within these conditions, the input voltage can range from  $V_{CC}$  to GND. Examples interfaces are illustrated below in a 50  $\Omega$  environment ( $Z = 50 \Omega$ )



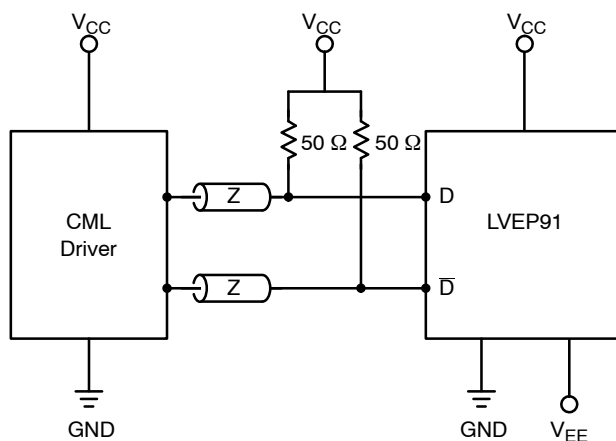
**Figure 6. Standard LVPECL Interface**



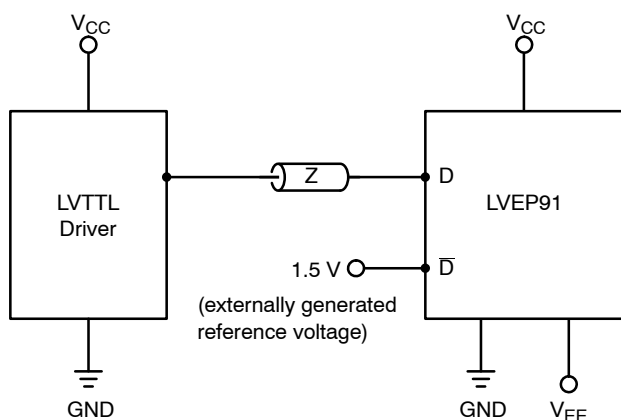
**Figure 7. Standard LVDS Interface**



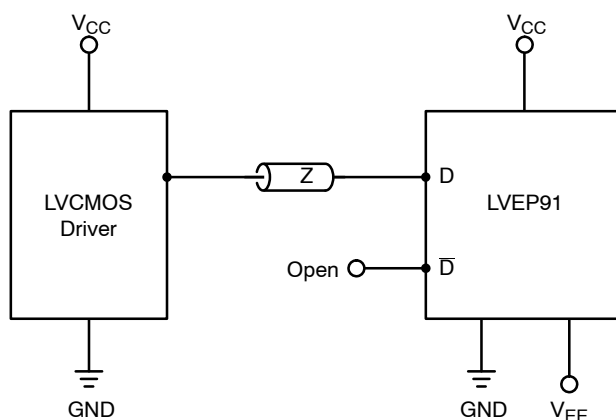
**Figure 8. Standard HSTL Interface**



**Figure 9. Standard 50  $\Omega$  Load CML Interface**

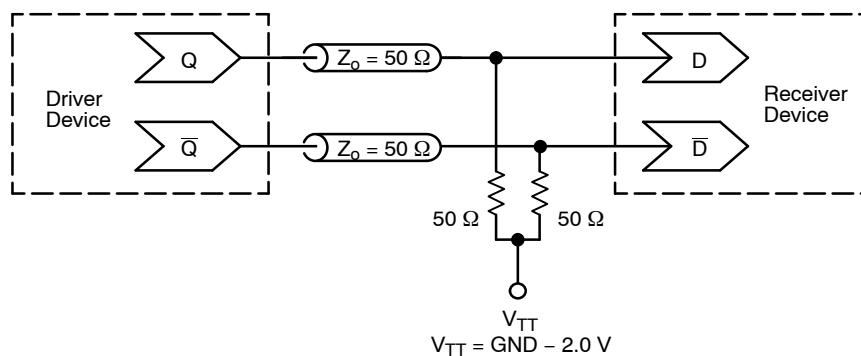


**Figure 10. Standard LVTTTL Interface**



**Figure 11. Standard LVC MOS Interface**  
( $\bar{D}$  Will Default to  $V_{CC}/2$  When Left Open.  
A Reference Voltage of  $V_{CC}/2$  Should be Applied to  $\bar{D}$  Input, if  $\bar{D}$  is Interfaced to CMOS Signals.)

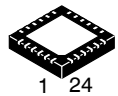
## NB100LVEP91



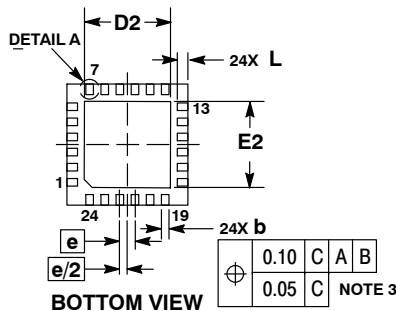
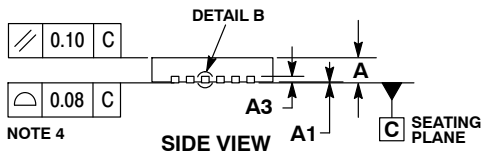
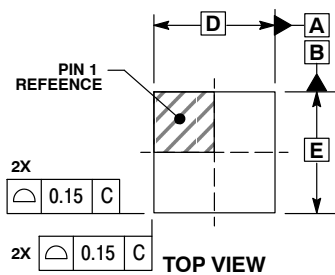
**Figure 12. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

### Resource Reference of Application Notes

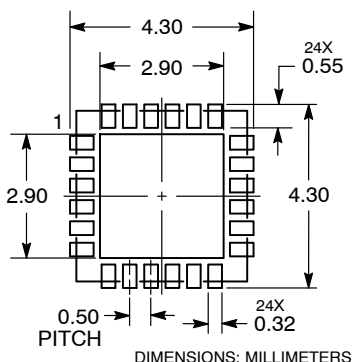
- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices



SCALE 2:1



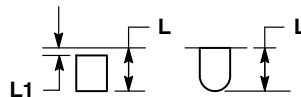
RECOMMENDED  
SOLDERING FOOTPRINT



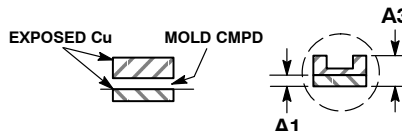
DIMENSIONS: MILLIMETERS

QFN24, 4x4, 0.5P  
CASE 485L  
ISSUE B

DATE 05 JUN 2012



DETAIL A  
ALTERNATE  
CONSTRUCTIONS



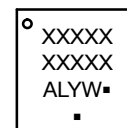
DETAIL B  
ALTERNATE TERMINAL  
CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.80        | 1.00 |
| A1  | 0.00        | 0.05 |
| A3  | 0.20        | REF  |
| b   | 0.20        | 0.30 |
| D   | 4.00        | BSC  |
| D2  | 2.70        | 2.90 |
| E   | 4.00        | BSC  |
| E2  | 2.70        | 2.90 |
| e   | 0.50        | BSC  |
| L   | 0.30        | 0.50 |
| L1  | 0.05        | 0.15 |

GENERIC  
MARKING DIAGRAM\*



XXXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

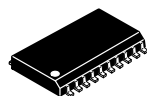
(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                  |                  |                                                                                                                                                                                     |
|------------------|------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| DOCUMENT NUMBER: | 98AON11783D      | Electronic versions are uncontrolled except when accessed directly from the Document Repository.<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION:     | QFN24, 4X4, 0.5P | PAGE 1 OF 1                                                                                                                                                                         |

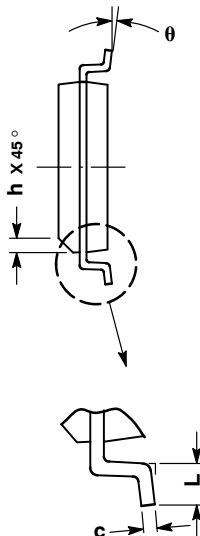
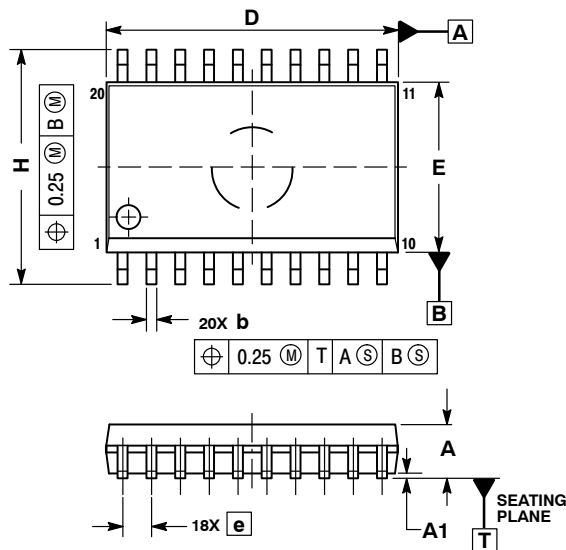
onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.



SCALE 1:1

SOIC-20 WB  
CASE 751D-05  
ISSUE H

DATE 22 APR 2015

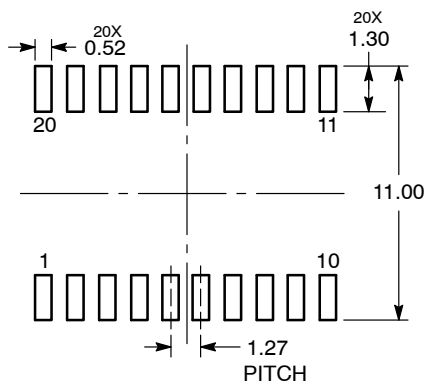


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS |       |
|-----|-------------|-------|
|     | MIN         | MAX   |
| A   | 2.35        | 2.65  |
| A1  | 0.10        | 0.25  |
| b   | 0.35        | 0.49  |
| c   | 0.23        | 0.32  |
| D   | 12.65       | 12.95 |
| E   | 7.40        | 7.60  |
| e   | 1.27 BSC    |       |
| H   | 10.05       | 10.55 |
| h   | 0.25        | 0.75  |
| L   | 0.50        | 0.90  |
| θ   | 0°          | 7°    |

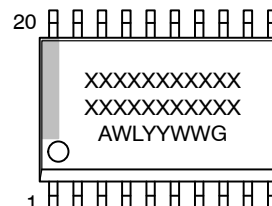
RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

|                  |             |                                                                                                                                                                                     |
|------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| DOCUMENT NUMBER: | 98ASB42343B | Electronic versions are uncontrolled except when accessed directly from the Document Repository.<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION:     | SOIC-20 WB  | PAGE 1 OF 1                                                                                                                                                                         |

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at  
[www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)